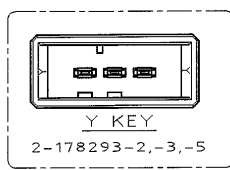
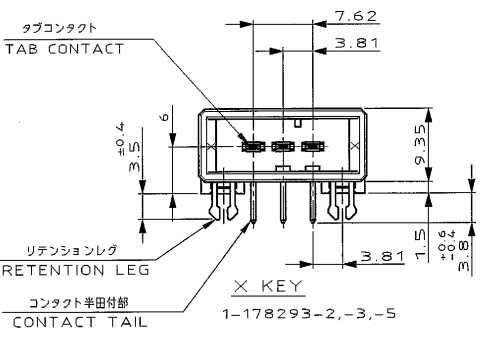
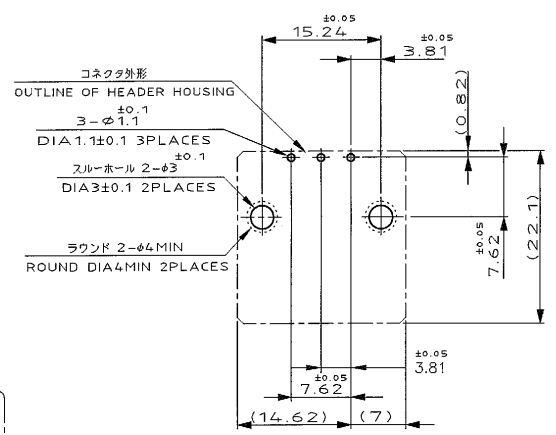
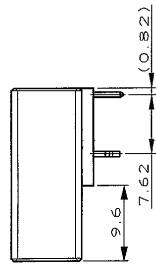
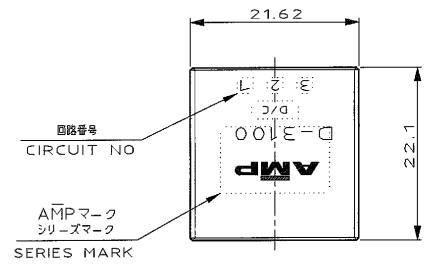


NUMBER 178293
 METRIC
 3-FI ANGLE PROJECTION
 DIMENSIONS IN MILLIMETERS. DO NOT SCALE PRINT
 PRINT DIST
 AMP-J
 REV.10/93



推奨基板取付け寸法
 PC 基板厚: 1.6±0.1
 (非累積公差)
 (コネクタ搭載面)

RECOMEND PC BOARD HOLE PATTERN
 PC BOARD THICKNESS: 1.6±0.1
 (NOT ACCUMULATE TOLERANCE)
 (CONNECTOR MOUNT SIDE)

NOTES

- MATERIAL: HOUSING: GLASS FILLED THERMO PLASTIC, POLYESTER
 CONTACT: COPPER ALLOY
 RETENTION LEG: COPPER ALLOY
- FINISH (CONTACT AREA): 0.38μm MIN GOLD PLATING OVER Ni PLATING
- FINISH (CONTACT AREA): 0.76μm MIN GOLD PLATING OVER Ni PLATING
- FINISH (CONTACT AREA): 2.0 μm MIN TIN PLATED OVER NICKEL
- FINISH (RETENTION LEG): TIN-LEAD PLATED (CONTACT TAIL) OVER NICKEL
- FINISH (RETENTION LEG): TIN PLATED (CONTACT TAIL) OVER NICKEL

注 記

- 材料: ハウジング: ガラス入り熱可塑性ポリエステル樹脂
 コンタクト: 銅合金
 リテンションレグ: 銅合金
- めっき: コンタクト: 全面Ni下地
 接触部: 0.38μm MIN金めっき
- めっき: コンタクト: 全面Ni下地
 接触部: 0.76μm MIN金めっき
- めっき: コンタクト: 全面Ni下地
 接触部: 2.0 μm MINスズめっき
- めっき: リテンションレグとコンタクト半田付部
 ——ニッケル下地の上に半田めっき——
- めっき: リテンションレグとコンタクト半田付部: ニッケル下地の上にスズめっき

△6	△4	1,2-178293-5
△6	△3	1,2-178293-3
△6	△2	1,2-178293-2
(FINISH)		部品番号 (PART NO.)

C	REVISED (FJDO-0039-03)	T S	S.M.	2/18/93
B	REVISED (FJDO-0097-03)	T S	S.M.	4/18/93
A	REDRAWN (FJ00-2183-95)	K I	S.M.	3-23/95
LTR	REVISION RECORD	DR	CHK	DATE

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tyco
 Electronics

Tyco Electronics AMP K.K.
 Kawasaki, Japan

WIRE RANGE	INSULATION DIA	NAME
—	—	—
MATERIAL	SEE NOTE	FINISH
—	—	—
3 POS SINGLE ROW HORIZONTAL HDR ASS'Y FOR DYNAMIC 3100		
—公差 (GENERAL TOLERANCE)	SIZE	LOC
10000 3007 20.3	A3	J
30000 10027 20.4	SCALE	NUMBER
50000 10027 20.5	2-1	C-178293
50000 10027 20.5	REV.	C
50000 10027 20.5	SHEET	1 OF 1

(CUSTOMER DRAWING) 顧客用図面